

# Manufacturing Review

## Call for papers

### Themed Issue on Advanced Manufacturing Research – Latest Developments

#### Edited by

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#### Background

To meet new demands for higher living and healthy standards and safety, meeting challenges in maintaining resource sustainability and protecting environment, and promoting better

communications and engagements, the product innovations have been accelerated, which promotes rapid advancements in manufacturing research and applications. New research activities have emerged and new applications have impacted significantly on our life and environment. These have progressed with an unprecedented pace. Keeping the pace with the frontier developments in manufacturing research would rely significantly on the effective dissemination of the research and application information among manufacturing communities and beyond.

## Aim/Objectives

The special issue seeks soliciting the papers from the ICMR2024 conference on both cutting-edge and emerging theoretical manufacturing research and its innovative applications with an aim to curate a collection highlighting the latest advances in the manufacturing research and applications, with focus on the new research findings and trends in manufacturing technique, process and system innovations.

We invite submissions from all of the following domains of research and innovative applications, but are not limited to:

- Manufacturing with Advanced/New Materials
- New Manufacturing Methods and Processes
- Advanced Manufacturing Technologies / New Manufacturing Techniques
- Advanced Manufacturing Systems, Smart/Intelligent/Digital/Cloud Manufacturing
- Sustainable Manufacturing & Remanufacturing Techniques & Circular Manufacturing
- AI/Machine Learning & Robotics for Manufacturing Process & System Innovation
- Safe and Sustainable by Design and its Integration with Manufacturing

## Submissions

All relevant papers will be carefully considered, vetted by a distinguished team of international experts, and published in accordance to the Journal's Ethical Standards. Full research papers and comprehensive review articles can be submitted online via the journal's submission and peer review site choosing, during the submission, the Topical issue 'Advanced Manufacturing Research – Latest Developments'.

Instructions for Authors at: <https://mfr.edp-open.org/author-information/instructions-for-authors>

## Article Processing Charges

Manufacturing Review is published in Open Access. An Article Processing Charge (APC) is applied. It covers the costs involved in the open access publication, such as editorial handling, copyediting, data management, proofs, administrative overheads and technologies in order to make your article findable, accessible, interoperable and reusable.

For accepted articles submitted in 2024, the APC is 700€ (paid after acceptance). The journal does not have any submission fee.

For manuscripts selected for submission from the ICMR2024 conference, we propose a reduced APC of 500 € (after acceptance).

### Other Waivers and Discounts

- EDP Sciences provides a waiver to authors based in countries included in Group A of the Research4Life programme
- EDP Sciences has signed an APC agreement with the NSLC (National Science Library CAS) the research library service system for the Chinese Academy of Sciences (CAS). Corresponding authors affiliated with one of the eligible CAS institutes, can publish in open access at a 20 percent discounted APC price.
- EDP Sciences has signed with the Technische Informationsbibliothek (TIB) a German National APC agreement. Corresponding authors affiliated with German academic institutions including universities and research institutions, can publish in open access at a 20 percent discounted APC price.
- Corresponding authors from French institutions having signed the National Open Access agreement in France, can publish in Open Access without any fee.

### Submission deadline – 30<sup>th</sup> September 2024

Article submission and editorial system [here](#).

### Abstracting/indexing

- [Astrophysics Data System \(ADS\)](#)
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